



# Product Change Notification

**Change Notification #:** 117066 - 01

**Change Title:** Intel® Server Chassis Hot Swap Drive Kit FUP4X35HSDK,  
Intel® Server Chassis Electrical Maintenance Kit FUPMESK,  
Intel® Server Fixed Fan Spare Kit FUPMNHFANPCI,  
Intel® Server Fixed Fan Spare Kit FUPNHFANCPU,  
Intel® Server Electrical Spare Kit FUPSESK,  
Intel® Server System Fan Kit FUPSNHFANE3,  
Intel® Server Trusted Platform Module AXXTPME6,  
Intel® Server Hot-swap Backplane Drive Cage Kit FUP8X25S3NVDK,  
Intel® Server Omni-Path Host Fabric Interface Adapter AHWKPTP100HF,  
Intel® Server 2U Bezel A2UBEZEL,  
Intel® Server Bridge Board AHWKPTP12GBGB,  
Intel® Server Bridge Board AHWKPTP12GBGBIT,  
Intel® Server Bridge Board AHWKPTP12GBGBR5,  
Intel® Server Breakout Board AHWKPTPBOB,  
Intel® Server Passive Heat-Sink AUPCWPBTP,  
Intel® Server I/O Module AXX1FDRIBIOM,  
Intel® Server I/O Module AXX2FDRIBIOM,

**Intel® Server Riser Card  
AXXKPTPIOM,  
Intel® Server Riser Card  
AXXKPTPM2IOM,  
Intel® Server Premium Rail AXXPRAIL,  
Intel® Server Premium Rail  
AXXPRAIL755,  
Intel® Server Trusted Platform Module  
AXXTPME5,  
Intel® Server Trusted Platform Module  
AXXTPME7,  
Intel® Server Custom Premium Rail  
EXX1U2URAILS2,  
Intel® Server Riser Card F1UL16RISER2,  
Intel® Server Spare Node Power Board  
FH2000NPB2,  
Intel® Server Spare Node Power Board  
FH2000NPB24,  
Intel® Server Backplane  
FHW16X25HS12G,  
Intel® Server Riser Card  
FHW1U16RISER2,  
Intel® Server Backplane FHW24X25HS12G,  
Intel® Server Bridge Board  
FHWKPTPBGB,  
Intel® Server Bridge Board  
FHWKPTPBGB24,  
Intel® Server Hot-Swap Drive Carrier  
FXX25HSCAR,  
Intel® Server Hot-Swap Drive Carrier  
FXX35HSADPB,  
Intel® Server Heat Sink FXXCA84X106HS,  
Intel® Server Heat Sink FXXCA91X91HS,  
Intel® Server Heat Sink FXXEA84X106HS,  
Intel® Server Heat Sink FXXEA91X91HS2,  
Intel® Server ODD Bay Bracket Kit  
AXXSSDODDKIT,  
Intel® Server Cable Kit  
AXXCBLEXPDMMS,**

**Intel® Server Cable Kit  
AXXCBL950HDMS,  
Intel® Server Cable Kit  
AXXCBL875HDMS,  
Intel® Server Cable Kit  
AXXCBL800HDMS,  
Intel® Server Cable Kit  
AXXCBL730MSMS,  
Intel® Server Cable Kit  
AXXCBL730HDMS,  
Intel® Server Cable Kit  
AXXCBL650MSMS,  
Intel® Server Cable Kit  
AXXCBL585HDMR,  
Intel® Server Cable Kit AXXCBL1UHRHD,  
Intel® Server Hot-swap Backplane  
FR1304S3HSBP,  
Intel® Server Rear Hot-swap Dual Drive  
A2UREARHSDK,  
Intel® Server Passive Airduct Kit  
AWTCOPRODUCT,  
Intel® Server ODD Bay Bracket Kit  
AXXSSDODDKIT,  
Intel® Server Switch Add-in Card  
AXX4PX8HDAIC,  
Intel® Server Hot-swap Backplane  
A2U44X25NVMEDK2,  
Intel® Server Hot-swap Backplane  
FXX8X25S3HSBP,  
Intel® Server Hot-swap Backplane  
F2U12X35S3HSBP,  
Intel® Server Hot-swap Drive Cage  
A2U44X25NVMEDK,  
Intel® Server Hot-swap Drive Cage  
A2U8X25S3HSDK,  
Intel® Server Hot-swap Drive Cage  
A2U8X35S3HSDK,  
Intel® Server Hot-swap Drive Cage  
A2U8X25S3DPDK,**

**Intel® Server Hot-swap Backplane  
F1U8X25S3HSBP,  
Intel® Server Switch Riser Card  
A1U2PXR3HDAIC,  
Intel® Server Hot-swap Backplane  
A1U44X25NVMEDK,  
Intel® Server Bezel A1UBEZEL,  
[Intel® Kit of Serial Port DB9 Adapters  
PCN 117066-01, Product Discontinuance,  
End of Life,  
Reason for Revision: Includes the Intel®  
Kit of Serial Port DB9 Adapters in PCN](#)**

**Date of Publication:** August 6, 2019

**Key Characteristics of the Change:**

Product Discontinuance

**Forecasted Key Milestones:**

<b>Product Discontinuance Program Support Begins:</b>	July 19, 2019
<b>Last Product Discontinuance Order Date:</b>	July 5, 2020
<b>Last Product Discontinuance Shipment Date:</b>	October 5, 2020
<b>Orders for Discontinued Products Become Non-Cancelable:</b>	April 5, 2020

**Description of Change to the Customer:**

**[Reason for Revision: Includes the Intel® Kit of Serial Port DB9 Adapters in PCN](#)**

Intel is announcing the discontinuance of the Intel® Server Spare kit listed in the "Products Affected/Intel Ordering Codes" table below.

Intel will make best efforts to support all orders placed between the Non-Cancelable and Non-Returnable (NCNR) and the Last Product Discontinuance Order (LPDO) dates. Intel will discontinue builds on the LPDO date. After the LPDO date existing inventory is still orderable, under NCNR terms, and will be filled on a first come first served basis. Deliveries must be accepted within 90 days from the LPDO date.

Final purchase orders are non-cancelable and non-returnable, notwithstanding any conflicting terms in our quotes, purchase order acknowledgement or Distributor agreements.

Intel reserves the right to change the products because of material source restriction.

[Update of this PCN includes the Intel® Kit of Serial Port DB9 Adapters as listed in table below.](#)

## Engineering and Support Guidance for Discontinued Products:

1. No new OS, peripheral or adaptor validation is planned during the extended life period. The THOL, supported processor and tested memory lists are frozen at PDA.
2. No new features enhancements should be expected, however ECOs may be required during the extended life period to maintain supply lines (e.g. to qualify new vendor due to a component EOL).
3. Intel will provide reasonable commercial efforts in debugging issues during the warranty period for the product after the PDA date has passed. Fixes cannot be committed, but Intel will endeavor to provide reasonable workarounds for the product.

## Customer Impact of Change and Recommended Action:

Determine your remaining demand for this product and/or evaluate additional sources (if applicable).

Lead-times on products with announced product discontinuance can typically stretch to 12 weeks and volumes are not buffered during the PDA period. Please work with your Intel representative on your quarterly demand forecast in order to reduce lead-times to 2-4 Weeks.

Please contact your local Intel Sales Office or Distributor if you require more information or need assistance in selecting a replacement product.

Milestone dates are estimates and subject to change based on business and operational conditions.

## Products Affected / Intel Ordering Codes:

Product Name	Product Code	MM#
Intel® I/O Module	AXX1FDRIBIOM	918607
TPM Module	AXXTPME5	919737
Intel® I/O Module	AXX2FDRIBIOM	920627
1U Spare Riser (1 slot)	F1UL16RISER2	934884
1U Spare Hot-swap Backplane	FR1304S3HSBP	934887
1U Spare Hot-swap Backplane	F1U8X25S3HSBP	934888
2U/4U Spare Hot-swap Backplane	FXX8X25S3HSBP	934890
2U Spare Hot-swap Backplane	F2U12X35S3HSBP	934893
1U Hot-swap Backplane Upgrade Kit	A1U44X25NVMEDK	936251
2U Hot-swap Drive Cage Upgrade Kit	A2U44X25NVMEDK	936253
TPM Module AXXTPME6	AXXTPME6	947921
TPM Module AXXTPME7	AXXTPME7	947922
Full-height, Low-profile PCIe* Switch	AXX4PX8HDAIC	947923
2U Hot-swap Backplane Upgrade Kit	A2U44X25NVMEDK2	947924
1U PCIe* Switch Riser 3 Card	A1U2PXR3HDAIC	984450
Pedestal Chassis Hot Swap Drive Kit	FUP4X35HSDK	911885
Spare 3.5in Hot-Swap HDD Carriers	FXX35HSADPB	912771
System Fan Kit FUPSNHFANE3	FUPSNHFANE3	912772
Electrical Spares Kit FUPSESK	FUPSESK	912774
Chassis Electrical Maintenance Kit	FUPMESK	915653
1U Bezel A1UBEZEL	A1UBEZEL	917983
2U Bezel A2UBEZEL	A2UBEZEL	918086
1U Heat Sink	FXXCA91X91HS	918250
1U Heat Sink	FXXCA84X106HS	918318
1U Heat Sink	FXXEA84X106HS	918321
Cable kit	AXXCBL650MSMS	918376
2.5in Hot-Swap Drive Carrier	FXX25HSCAR	918807
Fixed Fan Spare Kit FUPNHFANCPU	FUPNHFANCPU	919572
Fixed Fan Spare Kit FUPMNHFANPCI	FUPMNHFANPCI	919575
Cable kit AXXCBL730MSMS	AXXCBL730MSMS	921049

1U/2U Premium Rail	AXXPRAIL	924417
1U/2U Premium Rail	AXXPRAIL755	924418
Cable Kit AXXCBL730HDMS	AXXCBL730HDMS	927238
Rear Hot-swap Dual Drive Cage Upgrade	A2UREARHSDK	934976
Passive Airduct Kit AWT COPRODUCT	AWTCOPRODUCT	934988
ODD Bay Bracket Kit for Single SSD	AXXSSDODDKIT	935065
2U Hot-swap Drive Cage Upgrade Kit	A2U8X25S3HSDK	935066
2U Dual Port Hot-swap Drive Cage Upgrade	A2U8X25S3DPDK	935067
1U PCI Express rIOM Riser and rIOM	AXXKPTPIOM	935524
1U PCI Express Riser FHW1U16RISER2	FHW1U16RISER2	935565
Spare 12Gb SAS/SATA 16 x 2.5" Backplane	FHW16X25HS12G	935573
Spare Node Power Board FH2000NPB2	FH2000NPB2	935574
Bridge Board Spare FHWKPTPBGB	FHWKPTPBGB	935575
Spare 12Gb SAS Bridge Board AHWKPTP12GBG	AHWKPTP12GBGB	935580
2U Hot-swap Drive Cage Upgrade Kit	A2U8X35S3HSDK	936191
Breakout Board AHWKPTPBOB	AHWKPTPBOB	936274
Passive Heat-Sink AUPCWPBTP	AUPCWPBTP	936421
Hot-swap Backplane PCIe Combination	FUP8X25S3NVDK	936426
Cable Kit AXXCBLEXP HDMS	AXXCBLEXP HDMS	937127
Cable kit AXXCBL875HDMS	AXXCBL875HDMS	937130
Cable Kit AXXCBL950HDMS	AXXCBL950HDMS	937131
1U Heat Sink FXXEA91X91HS2	FXXEA91X91HS2	937228
Cable kit AXXCBL800HDMS	AXXCBL800HDMS	937309
Cable kit AXXCBL1UHRHD	AXXCBL1UHRHD	937311
Cable Kit AXXCBL585HDMR	AXXCBL585HDMR	937315
12Gb SAS Bridge Board	AHWKPTP12GBGBR5	937453
Custom 1U/2U Premium Rail EXX1U2URAILS	EXX1U2URAILS2	942266
Spare Node Power Board FH2000NPB24	FH2000NPB24	943480
Spare 12GB SAS 24 x 2.5" Backplane	FHW24X25HS12G	943481
Bridge Board Spare FHWKPTPBGB24	FHWKPTPBGB24	943482
1U PCI Express rIOM Riser and rIOM	AXXKPTPM2IOM	943483
Intel® Omni-Path Host Fabric Interface	AHWKPTP100HF	949054
Spare 12Gb SAS Bridge Board	AHWKPTP12GBGBIT	949475
<b>Kit of Serial Port DB9 Adapters</b>	<b>AXXRJ45DB93</b>	<b>920430</b>

## PCN Revision History:

Date of Revision:	Revision Number:	Reason:
July 19, 2019	00	Originally Published PCN
August 6, 2019	01	Includes the Intel® Kit of Serial Port DB9 Adapters in PCN



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## 117066 - 01

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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